

Octal Buffer/Line Driver with 3-State Outputs

MC74AC573, MC74ACT573

The MC74AC573/74ACT573 is a high-speed octal latch with buffered common Latch Enable (LE) and buffered common Output Enable (\overline{OE}) inputs.

The MC74AC573/74ACT573 is functionally identical to the MC74AC373/74ACT373 but has inputs and outputs on opposite sides.

Features

- Inputs and Outputs on Opposite Sides of Package Allowing Easy Interface with Microprocessors
- Useful as Input or Output Port for Microprocessors
- Functionally Identical to MC74AC373/74ACT373
- 3-State Outputs for Bus Interfacing
- Outputs Source/Sink 24 mA
- 'ACT573 Has TTL Compatible Inputs
- These are Pb-Free Devices

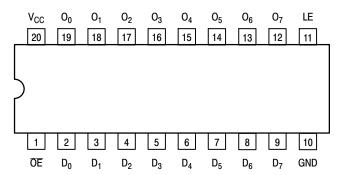


Figure 1. Pinout 20-Lead Packages Conductors

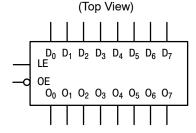


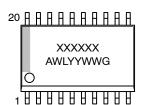
Figure 2. Logic Symbol

PIN ASSIGNMENT

PIN	FUNCTION			
D ₀ -D ₇	Data Inputs			
LE	Latch Enable Input			
ŌĒ	3-State Output Enable Input			
O ₀ -O ₇	3-State Latch Outputs			

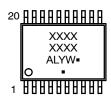
MARKING DIAGRAMS







TSSOP-20 DT SUFFIX CASE 948E



XXXXXX = Specific Device Code A = Assembly Location

WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

TRUTH TABLE

	Outputs		
OE	LE	D _n	O _n
L	Н	Н	Н
L	Н	L	L
L	L	Х	O ₀
Н	Х	X	Z

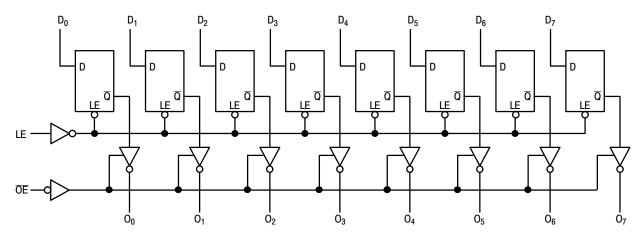
H = HIGH Voltage Level L = LOW Voltage Level Z = High Impedance

X = Immaterial

O₀ = Previous O₀ before LOW-to-HIGH Transition of Clock

Functional Description

The MC74AC573/74ACT574 contains eight D-type latches with 3-state output buffers. When the Latch Enable (LE) input is HIGH, data on the D_n inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW the latches store the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-state buffers are controlled by the Output Enable (\overline{OE}) input. When \overline{OE} is LOW, the buffers are enabled. When \overline{OE} is HIGH the buffers are in the high impedance mode but this does not interfere with entering new data into the latches.



NOTE: That this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS

Symbol	P	arameter	Value	Unit
V _{CC}	DC Supply Voltage (Referenced to Gl	ND)	-0.5 to +6.5	V
V _{IN}	DC Input Voltage (Referenced to GNI	0)	-0.5 to V _{CC} +0.5	V
V _{OUT}	DC Output Voltage (Referenced to Gi	ND) (Note 1)	-0.5 to V _{CC} +0.5	V
I _{IK}	DC Input Diode Current		±20	mA
lok	DC Output Diode Current		±50	mA
I _{OUT}	DC Output Sink/Source Current		±50	mA
I _{CC}	DC Supply Current, per Output Pin		±50	mA
I _{GND}	DC Ground Current, per Output Pin		±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead temperature, 1 mm from Case for	or 10 Seconds	260	°C
TJ	Junction Temperature Under Bias		140	°C
θЈА	Thermal Resistance (Note 2)	SOIC TSSOP	96 150	°C/W
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	UL 94 V-0 @ 0.125 in		
V _{ESD}	ESD Withstand Voltage	> 2000 > 1000	V	
I _{Latchup}	Latchup Performance	Above V _{CC} and Below GND at 85°C (Note 5)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. I_{OUT} absolute maximum rating must be observed.
- 2. The package thermal impedance is calculated in accordance with JESD 51-7.
- 3. Tested to EIA/JESD22-A114-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Тур	Max	Unit
.,			2.0	5.0	6.0	
V _{CC}	Supply Voltage	'ACT	4.5	5.0	5.5	V
V _{IN} , V _{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	-	V _{CC}	V
		V _{CC} @ 3.0 V	-	150	-	
t _r , t _f	put Rise and Fall Time (Note 1) C Devices except Schmitt Inputs	V _{CC} @ 4.5 V	-	40	-	ns/V
	The Bossess of the Bo	V _{CC} @ 5.5 V	-	25	-	
	Input Rise and Fall Time (Note 2)	V _{CC} @ 4.5 V	-	10	-	0 /
t _r , t _f	'ACT Devices except Schmitt Inputs	V _{CC} @ 5.5 V	-	8.0	-	ns/V
T _A	Operating Ambient Temperature Range		-40	25	85	°C
I _{OH}	Output Current - High		-	-	-24	mA
I _{OL}	Output Current – Low		-	-	24	mA

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

- V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
 V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

			74	AC	74AC		
Symbol	Parameter	V _{CC} (V)	T _A = +25°C		T _A = -40°C to +85°C	Unit	Conditions
			Тур	Guar	anteed Limits		
V _{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
V _{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	٧	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
V _{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	٧	I _{OUT} = -50 μA
		3.0 4.5 5.5	- - -	2.56 3.86 4.86	2.46 3.76 4.76	V	*V _{IN} = V _{IL} or V _{IH} -12 mA I _{OH} -24 mA -24 mA
V _{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	Ι _{ΟUT} = 50 μΑ
		3.0 4.5 5.5	- - -	0.36 0.36 0.36	0.44 0.44 0.44	V	*V _{IN} = V _{IL} or V _{IH} 12 mA I _{OL} 24 mA 24 mA
I _{IN}	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μΑ	$V_I = V_{CC}$, GND
l _{OZ}	Maximum 3-State Current	5.5	-	±0.5	±5.0	μΑ	$\begin{aligned} &V_{I}\left(OE\right)=V_{IL},V_{IH}\\ &V_{I}=V_{CC},GND\\ &V_{O}=V_{CC},GND \end{aligned}$
I _{OLD}	†Minimum Dynamic	5.5	-	-	75	mA	V _{OLD} = 1.65 V Max
I _{OHD}	Output Current	5.5	-	_	-75	mA	V _{OHD} = 3.85 V Min
Icc	Maximum Quiescent Supply Current	5.5	-	8.0	80	μΑ	V _{IN} = V _{CC} or GND

NOTE: I_{IN} and $I_{\text{CC}} @ 3.0 \text{ V}$ are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC} . *All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS

				74AC		74		
Symbol	Parameter	V _{CC} * (V)	T _A = +25°C C _L = 50 pF			T _A = - to +8 C _L = 8	35°C	Unit
			Min	Тур	Max	Min	Max	
t _{PLH}	Propagation Delay D _n to O _n	3.3 5.0	2.5 2.5	-	13.0 10.0	2.0 2.0	15.0 11.5	ns
t _{PHL}	Propagation Delay D _n to O _n	3.3 5.0	2.5 2.5	-	12.0 9.5	2.0 2.0	14.0 11.0	ns
t _{PLH}	Propagation Delay LE to O _n	3.3 5.0	2.5 2.5	-	13.0 9.5	2.0 2.0	15.0 11.0	ns
t _{PHL}	Propagation Delay LE to O _n	3.3 5.0	2.5 2.5	-	12.0 8.5	2.0 2.0	14.0 10.0	ns
t _{PZH}	Output Enable Time	3.3 5.0	2.5 2.5	-	11.0 9.0	2.0 2.0	12.0 10.0	ns
t _{PZL}	Output Enable Time	3.3 5.0	2.5 2.5		11.0 8.5	2.0 2.0	12.5 9.5	ns
t _{PHZ}	Output Disable Time	3.3 5.0	2.5 2.5	-	12.5 11.0	2.0 2.0	13.5 12.0	ns
t _{PLZ}	Output Disable Time	3.3 5.0	2.5 2.5	- -	9.5 8.0	2.0 2.0	10.5 9.0	ns

^{*}Voltage Range 3.3 V is 3.3 V ± 0.3 V. Voltage Range 5.0 V is 5.0 V ± 0.5 V.

AC OPERATING REQUIREMENTS

			74AC		74AC	
Symbol	Parameter	V _{CC} * (V)		ղ = +25°C L = 50 pF	T _A = -40°C to +85°C C _L = 50 pF	Unit
			Тур	Guaranteed	d Minimum	1
t _s	Setup Time, HIGH or LOW D _n to LE	3.3 5.0	-	3.5 3.0	4.0 3.5	ns
t _h	Hold Time, HIGH or LOW D _n to LE	3.3 5.0	-	2.0 2.0	2.0 2.0	ns
t _w	LE Pulse Width, HIGH	3.3 5.0	-	6.0 4.0	7.0 5.0	ns

^{*}Voltage Range 3.3 V is 3.3 V ± 0.3 V. Voltage Range 5.0 V is 5.0 V ± 0.5 V.

DC CHARACTERISTICS

			74	CT	74ACT		
Symbol	Parameter	V _{CC} (V)	T _A = +25°C		T _A = -40°C to +85°C	Unit	Conditions
			Тур	Guar	anteed Limits		
V _{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
V _{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	٧	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
V _{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	٧	I _{OUT} = -50 μA
		4.5 5.5	- -	3.86 4.86	3.76 4.76	V	$*V_{IN} = V_{IL} \text{ or } V_{IH}$ -24 mA I_{OH} -24 mA
V _{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I _{OUT} = 50 μA
		4.5 5.5	- -	0.36 0.36	0.44 0.44	V	$*V_{IN} = V_{IL} \text{ or } V_{IH}$ $^{1}_{OL} \qquad ^{24} \text{ mA}$ $^{24} \text{ mA}$
I _{IN}	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μΑ	V _I = V _{CC} , GND
ΔI_{CCT}	Additional Max. I _{CC} /Input	5.5	0.6	_	1.5	mA	V _I = V _{CC} – 2.1 V
l _{OZ}	Maximum 3-State Current	5.5	-	±0.5	±5.0	μΑ	$\begin{aligned} &V_{I}\left(OE\right) = V_{IL}, V_{IH} \\ &V_{I} = V_{CC}, GND \\ &V_{O} = V_{CC}, GND \end{aligned}$
I _{OLD}	†Minimum Dynamic	5.5	-	-	75	mA	V _{OLD} = 1.65 V Max
I _{OHD}	Output Current	5.5	-	-	-75	mA	V _{OHD} = 3.85 V Min
I _{CC}	Maximum Quiescent Supply Current	5.5	-	8.0	80	μΑ	V _{IN} = V _{CC} or GND

^{*}All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS

			74ACT			74ACT		
Symbol	Parameter	V _{CC} * (V)	T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF		Unit
			Min	Тур	Max	Min	Max	
t _{PLH}	Propagation Delay D _n to O _n	5.0	2.5	-	10.5	2.0	12	ns
t _{PHL}	Propagation Delay D _n to O _n	5.0	2.5	-	10.5	2.0	12	ns
t _{PLH}	Propagation Delay LE to O _n	5.0	3.0	-	10.5	2.5	12	ns
t _{PHL}	Propagation Delay LE to O _n	5.0	2.5	-	9.5	2.0	10.5	ns
t _{PZH}	Output Enable Time	5.0	2.0	-	10	1.5	11	ns
t _{PZL}	Output Enable Time	5.0	1.5	-	9.5	1.5	10.5	ns
t _{PHZ}	Output Disable Time	5.0	2.5	_	11	1.5	12.5	ns
t _{PLZ}	Output Disable Time	5.0	1.5	-	8.5	1.0	9.5	ns

^{*}Voltage Range 5.0 V is 5.0 V \pm 0.5 V.

AC OPERATING REQUIREMENTS

	Symbol Parameter			74ACT	74ACT	
Symbol			T,	ղ = +25°C L = 50 pF	T _A = -40°C to +85°C C _L = 50 pF	Unit
			Typ Guarantee		d Minimum	
t _s	Setup Time, HIGH or LOW D _n to LE	5.0	-	3.0	3.5	ns
t _h	Hold Time, HIGH or LOW D _n to LE	5.0	-	0	0	ns
t _w	LE Pulse Width, HIGH	5.0	-	3.5	4.0	ns

^{*}Voltage Range 5.0 V is 5.0 V \pm 0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C _{IN}	Input Capacitance	5.0	pF	V _{CC} = 5.0 V
C _{PD}	Power Dissipation Capacitance	25	pF	V _{CC} = 5.0 V

ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
MC74AC573DWG	AC573	SOIC-20	38 Units / Rail
MC74AC573DWR2G	AC573	SOIC-20	1000 Units / Tape & Reel
MC74AC573DTR2G	AC 573	TSSOP-20	2500 Units / Tape & Reel
MC74ACT573DWG	ACT573	SOIC-20	38 Units / Rail
MC74ACT573DWR2G	ACT573	SOIC-20	1000 Units / Tape & Reel
MC74ACT573DWR2G-Q*	ACT573	SOIC-20	1000 Units / Tape & Reel
MC74ACT573DTR2G	ACT 573	TSSOP-20	2500 Units / Tape & Reel

[†]For information on tape and reel specifications,including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

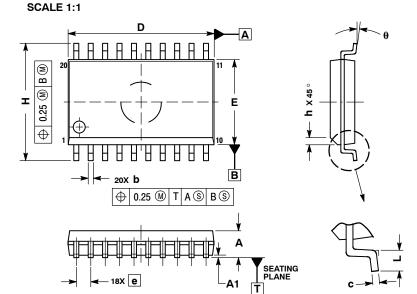
*-Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP





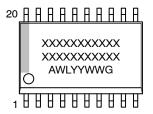
SOIC-20 WB CASE 751D-05 **ISSUE H**

DATE 22 APR 2015



- DIMENSIONS ARE IN MILLIMETERS.
 INTERPRET DIMENSIONS AND TOLERANCES.
- PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD
- PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL

	MILLIMETERS		
DIM	MIN	MAX	
Α	2.35	2.65	
A1	0.10	0.25	
b	0.35	0.49	
С	0.23	0.32	
D	12.65	12.95	
E	7.40	7.60	
е	1.27 BSC		
Н	10.05	10.55	
h	0.25	0.75	
L	0.50	0.90	
A	0 °	7 °	



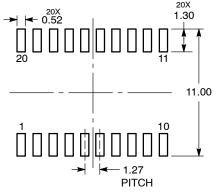
GENERIC MARKING DIAGRAM*

XXXXX = Specific Device Code = Assembly Location

WL = Wafer Lot ΥY = Year WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

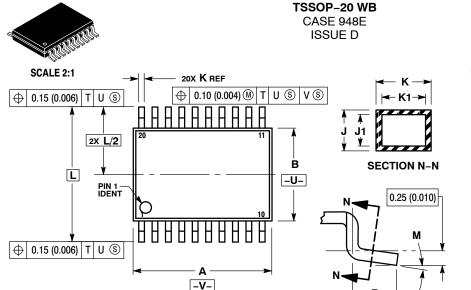
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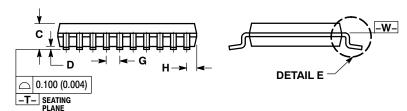
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^{*}For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DATE 17 FEB 2016







DETAIL E

NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

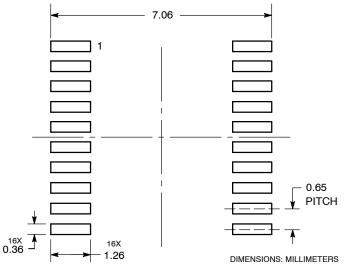
 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE
- INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 DIMENSION K DOES NOT INCLUDE
- DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K
 DIMENSION AT MAXIMUM MATERIAL CONDITION.
 TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE
 DETERMINED AT DATUM PLANE -W-.

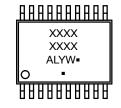
	MILLIN	IETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.27	0.37	0.011	0.015
7	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

RECOMMENDED SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



= Assembly Location

= Wafer Lot

= Year

= Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.

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